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James jian-qiang lu, ieee fellow, 3d ic; 3d tsv

in 2003 IEEE International Interconnect Technology Conference in International Electronic Packaging Technical Conference 8th Street , Troy, NY 12180

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The wire sag problem in wire bonding technology

Proceeding of 8th electronic packaging technology electronic packaging technology conference packaging.
Microelectron Eng, 83 (10) (2006)

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